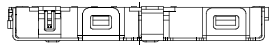
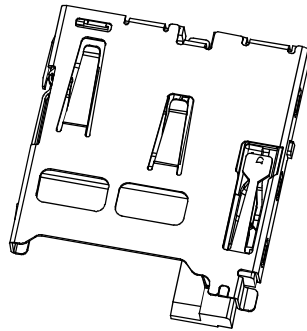
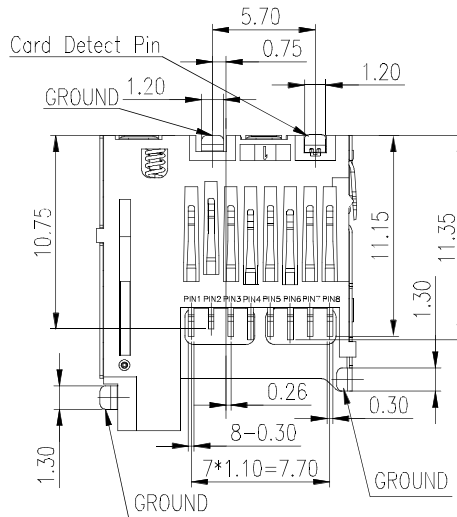
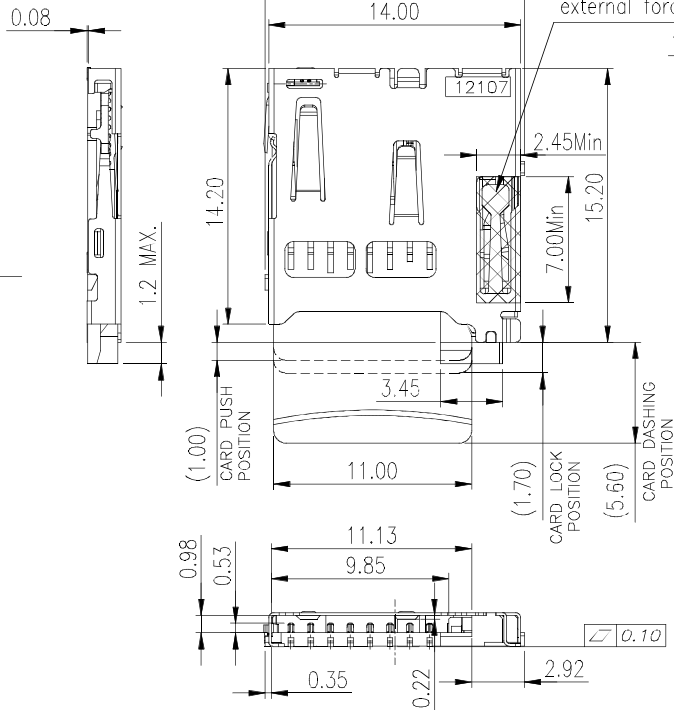


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The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00759 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



The shrapnel areas prohibit contact and extruded by the external force



PIN No.	FUNCTION
PIN 1	DAT2
PIN 2	CD/DAT3
PIN 3	CMD
PIN 4	VDD
PIN 5	CLK
PIN 6	VSS
PIN 7	DAT0
PIN 8	DAT1

PART NO. GTFP084 X X BEU

CONTACT FINISH
2: 10 μ " GOLD
3: 15 μ " GOLD
4: 30 μ " GOLD

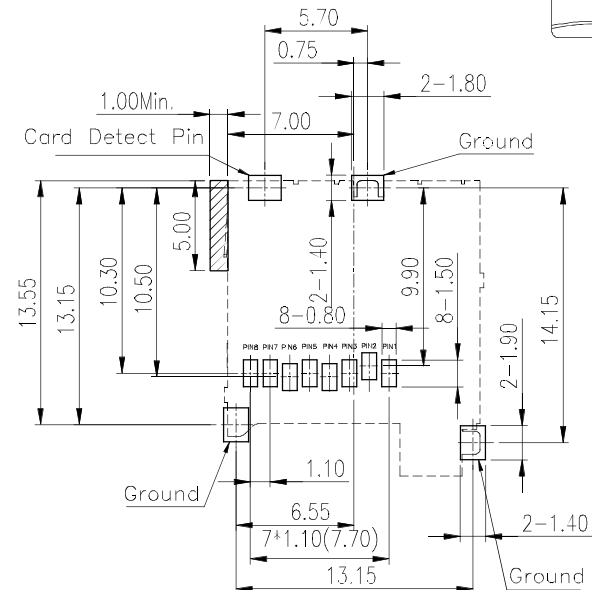
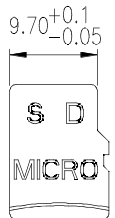
PACKING STYLE
1: W/O MYLAR T&R
2: W/ MYLAR T&R

RECOMMENDED SOLDER PAD AREA
DEVICE KEEP OUT AREA

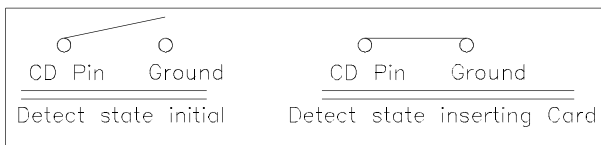
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-12202	UNAPPROVED REVISION	11/13/2012	Arron Lin
B	NE-13080	UPDATE DRAWING	05/24/2013	Arron Lin
C	NE-13101	ADDED DIM AND 30u" GOLD PLATING	07/08/2013	Arron Lin
D	NE-14226	MODIFY DESING FOR PIN2 N/F AND CD PIN RETENTION.	12/23/2014	Arron Lin
E	NE-15134	REMOVE SHELL RIB MEET THE CURRENT	11/03/2015	Arron Lin
F	NE-17179	CHANGE CARD LATCH FROM SIDE TYPE	07/14/2017	Roger Tsai

NOTES:

1. INSULATOR: HIGH TEMPERATURE THERMOPLASTIC, LCP, UL 94V-0, COLOR- BLACK.
2. CONTACT: COPPER ALLOY, SELECTIVE GOLD PLATING ON CONTACT AREA, MATTE TIN PLATING 100u" ON SOLDERING AREA.
3. SHELL: STEEL (SUS 301), NI PLATING 50u" ON SOLDERING AREA.
4. THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
5. RECOMMED SD CARD WIDTH IS DIM 9.70^{+0.1}_{-0.05} FOR TEST.
6. PRODUCT SPECIFICATION REFER TO : PS-7500.
7. TEST SUMMARY REFER TO : TS-7500-001.



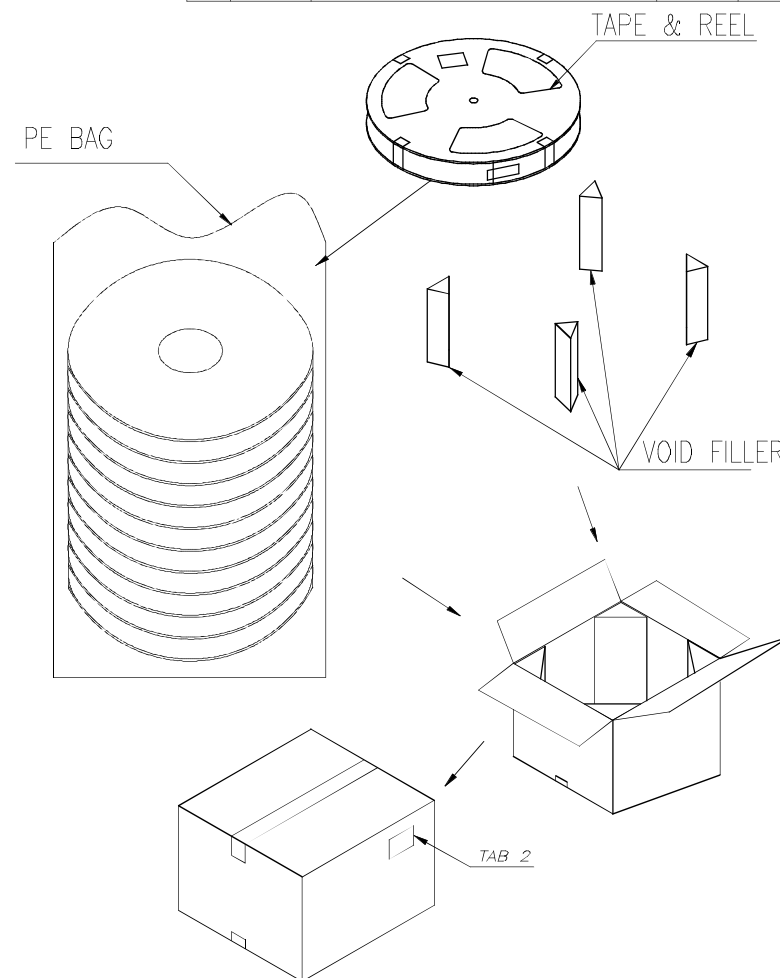
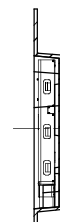
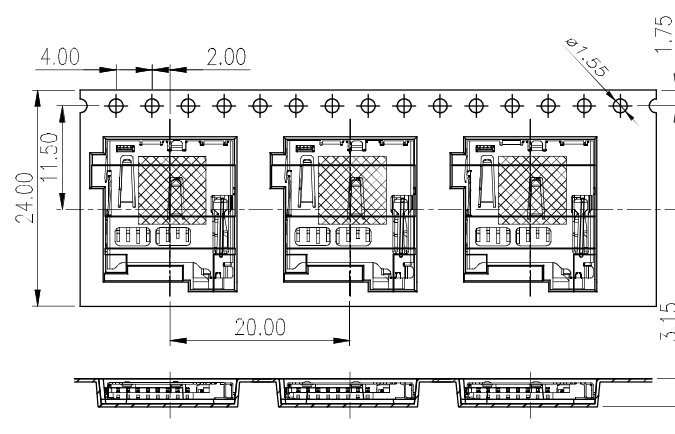
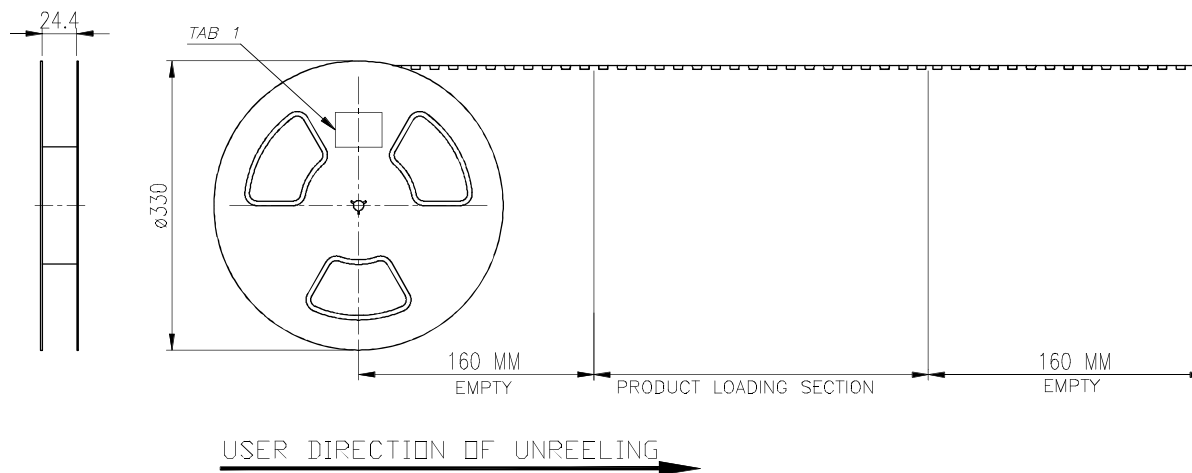
RECOMMENDED PCB LAYOUT
(CALL TOLERANCE AFE ± 0.05 mm)
TOP VIEW



TOLERANCE	APPROVALS	DATE	TITLE		PART No.			
X. X.X X.XX X.XXX	DRAWN Karen Su	07/14/2017	MICRO SD NORMAL OPEN TYPE (HEIGHT IS 1.85 MM)		GTFP084XXBEU			
ANGULAR $\pm 1^\circ$	CHECKED Aqua Chou	07/14/2017						
UNLESS OTHERWISE SPECIFIED	APPROVED Roger Tsai	07/14/2017						
	DWG TYPE CUST DWG	PROJECT CODE OTHER	UNIT mm	SIZE A3	SHEET 1 OF 2	DWG No.	GTFP084XXBEU	REV. F

The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-12202	UNAPPROVED REVISION	11/13/2012	Arron Lin
B	NE-13080	UPDATE DRAWING	05/24/2013	Arron Lin
C	NE-13101	ADDED DIM AND 30u" GOLD PLATING	07/08/2013	Arron Lin
D	NE-14226	MODIFY DESING FOR PIN2 N/F AND CD PIN RETENTION.	12/23/2014	Arron Lin
E	NE-15134	REMOVE SHELL RIB MEET THE CURRENT	11/03/2015	Arron Lin
F	NE-17179	CHANGE CAD LATCH FROM SIDE TYPE	07/14/2017	Roger Tsai



F/N(1P) :	
Q'TY(Q) :	
F/O(K) :	
DATE : MM/DD/YYYY	RoHS
G.W. : XXX KG	
Amphenol Taiwan Corporation	

TAB2: CARTON LABEL
(CONTENT BY ACTUAL)

F/N(1P) :		■■■■■■■■■■
Q/TY(Q) :		■■■
F/O(K) :		■■■■■■■■■■■■■■■■■■■■
DATE : MM/DD/YYYY		RoHS
G.W. : XXX KG		
Amphenol Taiwan Corporation		

TAB1: REEL LABEL
(CONTENT BY ACTUAL)

PACKAGING BY TAPE&REEL	5.5	2.18	1000	5	5000	GTFP084XXBEU
	G/W KG	N/W KG	PCS/ REEL	REELS/ CARTON	QUANTITY (PCS)	PART NUMBER

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol® Amphenol Corporation Amphenol Taiwan Corporation	
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10	DRAWN	Karen Su	07/14/2017	MICRO SD NORMAL OPEN TYPE (HEIGHT IS 1.85 MM)				
	CHECKED	Aqua Chou	07/14/2017					
	APPROVED	Roger Tsai	07/14/2017					
ANGULAR ±1°				UNIT	mm	SIZE	A3	PART No. GTFP084XXBEU
UNLESS OTHERWISE SPECIFIED	DWG TYPE	CUST DWG	PROJECT CODE	OTHER	SCALE	NA	SHEET	2 OF 2
					DWG No.	GTFP084XXBEU		REV. F